

PATENT APPLICATION TRANSMITTAL LETTER
(Large Entity)

Docket No.
MM4640

TO THE ASSISTANT COMMISSIONER FOR PATENTS

Transmitted herewith for filing under 35 U.S.C. 111 and 37 C.F.R. 1.53 is the patent application of:

Chung-Che TSAI

For: **WINDOW BALL GRID ARRAY SEMICONDUCTOR PACKAGE WITH SUBSTRATE HAVING OPENING
AND METHOD FOR FABRICATING THE SAME**

Enclosed are:

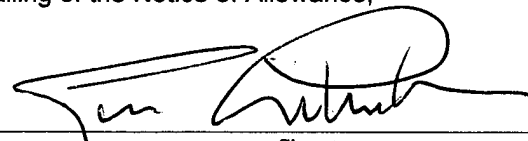
- ☒ Certificate of Mailing with Express Mail Mailing Label No. **EV331920700US**
- ☒ **9 (Figs. 1-4F)** sheets of drawings.
- ☐ A certified copy of a _____ application.
- ☒ Declaration ☒ Signed. ☐ Unsigned.
- ☒ Power of Attorney
- ☐ Information Disclosure Statement
- ☐ Preliminary Amendment
- ☒ Other: **Assignment document with recordation form cover sheet**

CLAIMS AS FILED

| For | #Filed | #Allowed | #Extra | Rate | Fee |
|---|--------|----------|--------|-----------|----------|
| Total Claims | 19 | - 20 = | 0 | x \$18.00 | \$0.00 |
| Indep. Claims | 2 | - 3 = | 0 | x \$84.00 | \$0.00 |
| Multiple Dependent Claims (check if applicable) <input type="checkbox"/> | | | | | \$0.00 |
| BASIC FEE | | | | | \$750.00 |
| TOTAL FILING FEE | | | | | \$750.00 |

- ☐ A check in the amount of _____ to cover the filing fee is enclosed.
- ☒ The Commissioner is hereby authorized to charge and credit Deposit Account No. **01-1944** as described below. A duplicate copy of this sheet is enclosed.
 - ☒ Charge the amount of **\$750.00** as filing fee.
 - ☒ Credit any overpayment.
 - ☒ Charge any additional filing fees required under 37 C.F.R. 1.16 and 1.17.
 - ☐ Charge the issue fee set in 37 C.F.R. 1.18 at the mailing of the Notice of Allowance, pursuant to 37 C.F.R. 1.311(b).


Dated: **September 24, 2003**



Signature
Eugene Lieberstein Reg. No. 24,645

cc:

22386 U.S. PTO
10/671176
09/24/03

| | | | |
|---|--------------------------------------|----------|-----------------------------|
| CERTIFICATE OF MAILING BY "EXPRESS MAIL" (37 CFR 1.10) Applicant(s): Chung-Che TSAI | | | Docket No. MM4640 |
| Serial No. | Filing Date Concurrently Herewith | Examiner | Group Art Unit |
| Invention: WINDOW BALL GRID ARRAY SEMICONDUCTOR PACKAGE WITH SUBSTRATE HAVING OPENING OPENING AND METHOD FOR OPENING AND METHOD FOR FABRICATING THE SAME | | | |
| <p>I hereby certify that this <u>New U.S. Patent Application with enclosures.</u> <i>(Identify type of correspondence)</i></p> <p>is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 in an envelope addressed to: The Commissioner of Patents and Trademarks, Washington, D.C. 20231-0001 on <u>September 24, 2003</u> <i>(Date)</i></p> <p><u>Maggie McGarry</u> <i>(Typed or Printed Name of Person Mailing Correspondence)</i></p> <p><u></u> <i>(Signature of Person Mailing Correspondence)</i></p> <p><u>EV331920700US</u> <i>("Express Mail" Mailing Label Number)</i></p> | | | |
| <p>Note: Each paper must have its own certificate of mailing.</p> | | | |